

# Electronics Protection

## 2010 Editorial Calendar

ISSUE CLOSE DATES	TECHNOLOGY FEATURE	MARKET FOCUS	PRODUCTS/ SERVICES SHOWCASE	EVENT DISTRIBUTION <i>Partial List - Subject to Change</i>
<u>Resource Guide</u> Space Close: 11/25/09 Materials Due: 12/2/09	<ul style="list-style-type: none"> <li>• Security</li> <li>• Thermal Protection</li> <li>• Connectors</li> <li>• Compliance</li> </ul>	<ul style="list-style-type: none"> <li>• Telecom</li> <li>• Harsh Environments</li> </ul>	<u>New Products in Every Issue include:</u> <ul style="list-style-type: none"> <li>■ Enclosures</li> <li>■ Thermal Protection</li> <li>■ Shielding</li> <li>■ EMI/EMC/ESD</li> <li>■ Contamination Protection</li> <li>■ Shock/Vibration Protection</li> <li>■ Power Protection</li> <li>■ Environmental Protection</li> <li>■ Enclosure Hardware/Software</li> <li>■ Data Protection</li> <li>■ Condition Monitoring</li> <li>■ Predictive/Preventative Maintenance</li> </ul>	<ul style="list-style-type: none"> <li>• Pacific Design &amp; Mfg.</li> <li>• APEC</li> <li>• CMSE</li> </ul>
<b>Annual Resource Guide</b>				
<u>March/April</u> Space Close: 1/28/10 Materials Due: 2/4/10	<ul style="list-style-type: none"> <li>• Non-Metal Enclosures</li> <li>• Shock/Vibration Protection</li> <li>• Circuit &amp; Surge Protection</li> </ul>	<ul style="list-style-type: none"> <li>• Electrical/Utility</li> <li>• Mission Critical Infrastructure</li> <li>• Consumer &amp; Commercial Electronics</li> </ul>		<ul style="list-style-type: none"> <li>• APEX</li> <li>• Embedded Systems Conf.</li> <li>• NAB</li> <li>• EDS</li> <li>• ECTC</li> <li>• INTEROP Las Vegas</li> <li>• PowderMet</li> </ul>
<u>June/July</u> Space Close: 4/29/10 Materials Due: 5/6/10	<ul style="list-style-type: none"> <li>• Thermal Protection</li> <li>• Cases</li> <li>• EMI/EMC/ESD</li> <li>• Electronics Packaging</li> </ul>	<ul style="list-style-type: none"> <li>• Military/Aerospace</li> <li>• Harsh Environments</li> </ul>		<ul style="list-style-type: none"> <li>• EOS/ESD Symposium</li> <li>• IEEE-EMC 2010</li> </ul>
<u>September/October</u> Space Close: 7/29/10 Materials Due: 8/5/10	<ul style="list-style-type: none"> <li>• Power Protection &amp; Distribution &amp; Monitoring</li> <li>• Coatings &amp; Encapsulants</li> <li>• Hardware</li> <li>• Contamination Protection</li> </ul>	<ul style="list-style-type: none"> <li>• Industrial/Manufacturing</li> <li>• Equipment Reliability</li> </ul>		<ul style="list-style-type: none"> <li>• Design &amp; Manufacturing Midwest</li> <li>• INTEROP</li> </ul>
<u>November/December</u> Space Close: 9/27/10 Materials Due: 9/30/10	<ul style="list-style-type: none"> <li>• Enclosure Design &amp; Fabrication</li> <li>• Test/Condition Monitoring</li> <li>• Shielding</li> </ul>	<ul style="list-style-type: none"> <li>• Network/Data Centers</li> </ul>		

**In Every Issue:**

- New Product Announcements
- Application and Technology Features
- Industry News
- Company Profiles
- Market Research Report Data
- Plus Much More!!

For editorial information, contact Nick Depperschmidt at 800-803-9488, ext. 111, nickd@infowebcom.com  
 For advertising information, contact Laura Mayo at 800-803-9488, ext. 130, lauram@infowebcom.com

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Webcom Communications Corp. • 7355 E. Orchard Rd., Suite 100 • Greenwood Village, CO 80111  
 800-803-9488 or 720-528-3770 • Fax 720-528-3771 • www.infowebcom.com

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